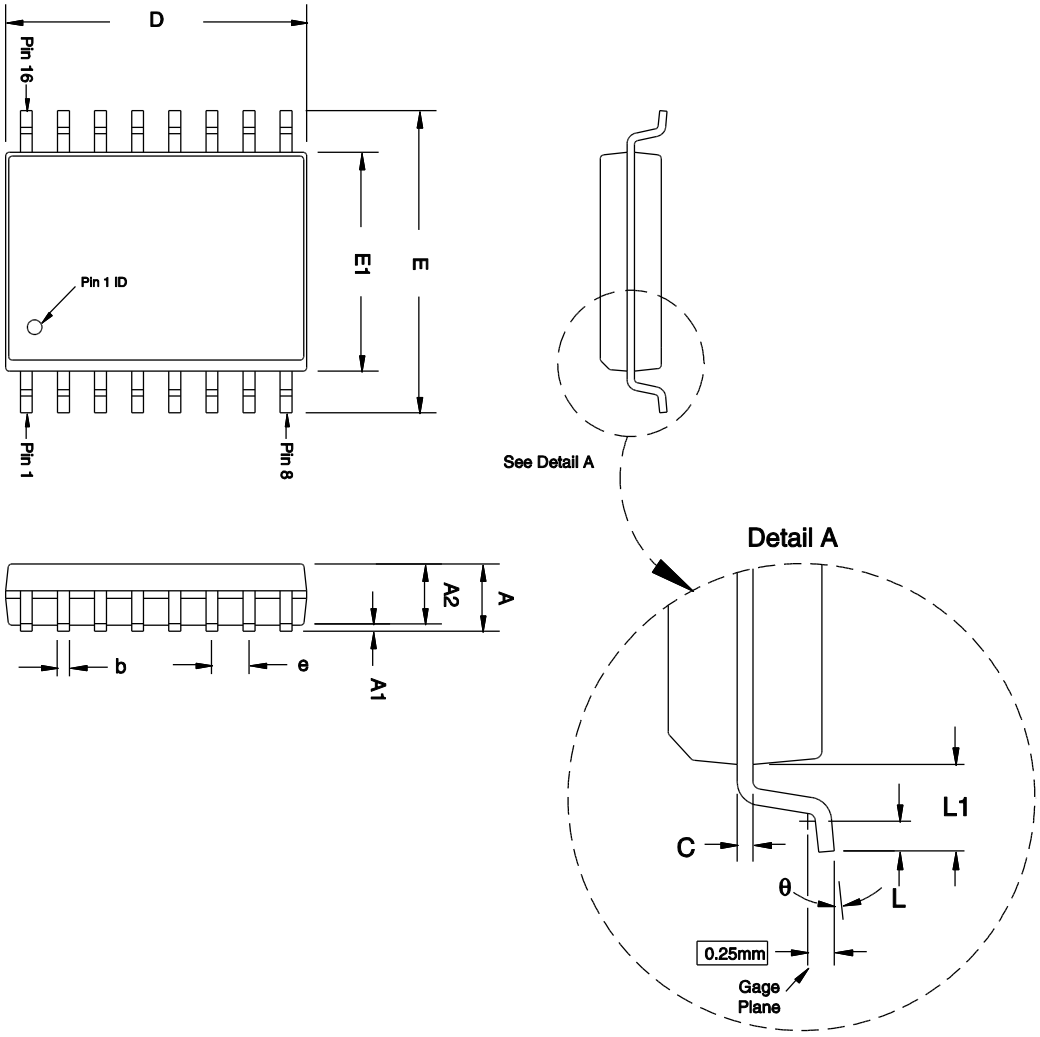
16-Pin Small Outline Integrated Circuit Package (SOIC) - Wire Bond

- All dimensions and tolerances conform to ASME Y14.5M – 1994.
- Controlling dimension is in millimeters.
- Pin 1 may be indicated by an ID dot, or a special feature, in its proximity on package surface.

Package Information	
Description	**Specification**
Ordering Code Reference	S
Package Acronym	SOIC
Substrate Material	Copper
Lead Finish (plating)	Pb-free: Matte Tin (Annealed)
JEDEC Outline Reference	MS-013 Variation: AA
Lead Coplanarity	0.1 mm
Weight	0.4g (Typ.)
Moisture Sensitivity Level	Printed on moisture barrier bag

Package Outline Dimension Table			
Symbol	**Millimeters**		
	Min.	**Nom.**	**Max.**
A	2.35	-	2.65
A1	0.10	-	0.30
A2	2.05	-	2.55
D	10.08	-	10.49
E	10.01	-	10.64
E1	7.39	-	7.59
L	0.38	-	1.27
L1	1.40 REF		
b	0.31	-	0.51
c	0.20	-	0.33
e	1.27 BSC		
θ	0°	-	8°

Package Outline



Document Revision History

Table 1 shows the revision history for this document.

Table 1. Document Revision History

Date	Version	Changes
October 2017	1.0	Initial release

now part of Intel

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